

For automotive components
high heat resistance multi-layer circuit board materials

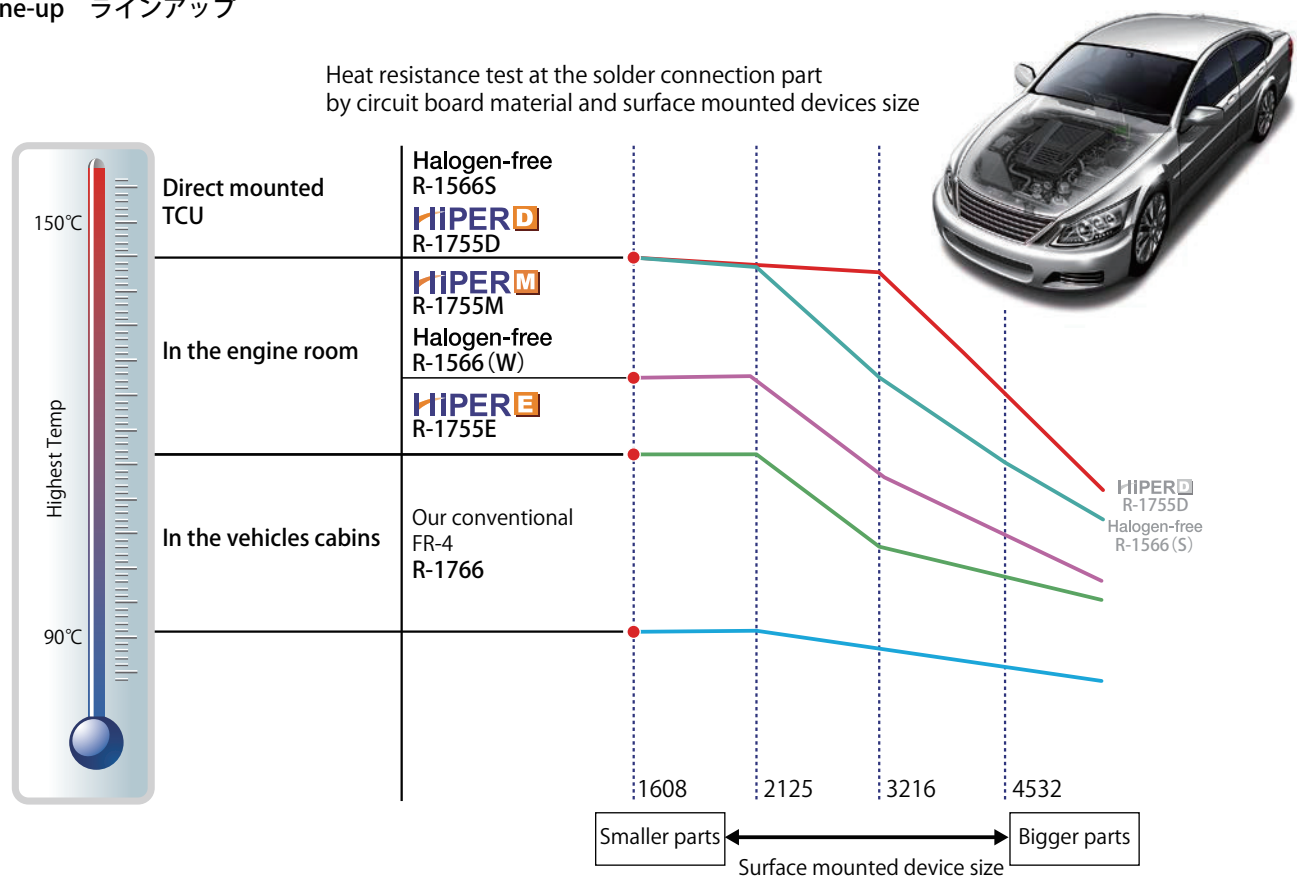
車載機器向け 高耐熱多層基板材料

HIPER Series
シリーズ

Lineup of multi-layer circuit board materials with excellent high heat resistance and high reliability.

高信頼性と高耐熱性に優れた多層基板材料をラインアップ

Line-up ラインアップ



General properties 一般特性

Item	Test method	Condition	Unit	Halogen-free R-1566S	HIPER D R-1755D	HIPER M R-1755M	Halogen-free R-1566(W)	HIPER E R-1755E	Conventional FR-4 R-1766	
Glass transition temp.(Tg)	DSC	A	°C	175	163	153	148	133	140	
CTE x-axis	α1 IPC-TM-650 2.4.41	A	ppm/°C	11-13	10-12	11-13	11-13	11-13	11-13	
CTE y-axis				13-15	12-14	13-15	13-15	13-15	13-15	
CTE z-axis	α1	A		40	43	40	40	40	42	65
	α2			180	236	240	180	250	270	
T288(with copper)	IPC-TM-650 2.4.24.1	A	min	10	15	18	3	25	1	
Peel strength	1oz(35μm)	IPC-TM-650 2.4.8	A	kN/m	1.6	1.3	1.5	1.8	1.6	2.0

The sample thickness is 0.8mm.

More Product line from Panasonic 関連商品

Please see the page for "Notes before you use" 商品のご採用に当たっての注意事項はこちら

- High heat resistance phenolic molding compounds
- For ICT infrastructure equipment multi-layer materials MEGTRON Series
- For mobile products and automotive components flexible materials FELIOS LCP
- For automotive components and mobile product halogen-free multi-layer materials

- 高耐熱フェノール樹脂成形材料
- ICTインフラ機器向け基板材料 MEGTRONシリーズ
- モバイル機器・車載機器向けLCPフレキシブル基板材料
- 車載機器・モバイル機器向けハロゲンフリー多層基板材料

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